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IC Knowledge – IC Cost and Price Model Supported Processes List

As of the 2017 IC Cost and Price Model revision 03 the following processes are included in the model.

The syntax is: process number – wafer size – node – company name – company process name (if applicable) – process type – process details (if applicable) – poly layers – metal layers/type

A glossary of abbreviations used in the process description is provided in the model manual.

1. 100mm - 3.0 μ m - Generic - NA - Bipolar - NA - 0P/2AI
2. 100mm - 3.0 μ m - Generic - NA - CMOS - NA - 1P/1AI
3. 100mm - 2.0 μ m - Generic - NA - CMOS - NA - 1P/2AI
4. 100mm - 2.0 μ m - Generic - NA - NMOS - NA - 1P/2AI
5. 125mm - 3.0 μ m - Generic - NA - Bipolar - NA - 0P/2AI
6. 125mm - 3.0 μ m - Generic - NA - CMOS - NA - 1P/1AI
7. 125mm - 2.0 μ m - Generic - NA - CMOS - NA - 1P/2AI
8. 125mm - 2.0 μ m - NXP - NA - Bipolar - NA - 0P/2AI
9. 125mm - 1.2 μ m - Generic - NA - BiCMOS - NA - 1P/2AI
10. 150mm - 5.0 μ m - Infineon - NA - Bipolar - NA - 0P/2AI
11. 150mm - 4.0 μ m - Polar Fab - BP14 - Bipolar - NA - 0P/1AI
12. 150mm - 4.0 μ m - Polar Fab - BP14 - Bipolar - NA - 0P/2AI
13. 150mm - 3.0 μ m - Denso - NA - BiCMOS SOI - NA - 1P/3AI
14. 150mm - 3.0 μ m - Generic - NA - Bipolar - NA - 0P/2AI
15. 150mm - 2.0 μ m - Generic - NA - Bipolar - NA - 0P/2AI
16. 150mm - 2.0 μ m - Generic - NA - CMOS - NA - 1P/2AI
17. 150mm - 1.5 μ m - Generic - NA - CMOS - NA - 1P/2AI
18. 150mm - 1.25 μ m - Polar Fab - BP30 - Bipolar - 30V - 0P/1AI
19. 150mm - 1.25 μ m - Polar Fab - BP30 - Bipolar - 30V - 0P/2AI
20. 150mm - 1.2 μ m - Bosch - NA - CMOS - NA - 1P/3AI
21. 150mm - 1.2 μ m - Denso - NA - BiCMOS - NA - 1P/3AI
22. 150mm - 1.2 μ m - Generic - NA - CMOS - NA - 1P/2AI
23. 150mm - 1.2 μ m - On Semi (AMI) - NA - BiCMOS - NA - 1P/2AI
24. 150mm - 1.0 μ m - Bosch - NA - CMOS - NA - 1P/3AI
25. 150mm - 1.0 μ m - STMicro - NA - CMOS - NA - 1P/2AI
26. 150mm - 1.0 μ m - Tower - TS100 - CMOS - NA - 1P/2AI
27. 150mm - 1.0 μ m - X-Fab - XC10 - CMOS - Pressure Sensor - 2P/2AI
28. 150mm - 800nm - ASMC - NA - BiCMOS - NA - 1P/3AI
29. 150mm - 800nm - Bosch - NA - CMOS - NA - 1P/3AI
30. 150mm - 800nm - Freescale - SMOS5 - CMOS - NA - 1P/2AI

31. 150mm - 800nm - Generic - NA - CMOS - NA - 1P/2Al
32. 150mm - 800nm - Generic - NA - CMOS - NA - 1P/3Al
33. 150mm - 800nm - Polar Fab - ABC3 - BiCMOS - NA - 1P/2Al
34. 150mm - 800nm - Polar Fab - ABC3 - BiCMOS - NA - 1P/3Al
35. 150mm - 800nm - Polar Fab - RFBC - BiCMOS - RF - 2P/2Al
36. 150mm - 800nm - Polar Fab - RFBC - BiCMOS - RF - 2P/3Al
37. 150mm - 800nm - STMicro - NA - CMOS - NA - 1P/3Al
38. 150mm - 800nm - Tower - TS80M - CMOS - NA - 2P/3Al
39. 150mm - 700nm - On Semi (AMI) - I2T30 - BiCMOS - 30V - 1P/2Al
40. 150mm - 700nm - On Semi (AMI) - I2T30E - BiCMOS - 30V - 2P/2Al
41. 150mm - 700nm - On Semi (AMI) - I2T60 - BiCMOS - 60V - 2P/2Al
42. 150mm - 700nm - On Semi (AMI) - I2T100 - BiCMOS - 100V - 2P/2Al
43. 150mm - 600nm - ADI - EP135 - BiCMOS - Comp,TFR, PPCaps - 1P/3Al
44. 150mm - 600nm - Tower - TS60M - CMOS - NA - 2P/3Al
45. 150mm - 600nm - TSMC - NA - CMOS - NA - 1P/2Al
46. 150mm - 600nm - X-Fab - CX06 - CMOS - NA - 1P/3Al
47. 150mm - 600nm - X-Fab - XB06 - BiCMOS - NA - 2P/3Al
48. 150mm - 600nm - X-Fab - XC06 - CMOS - eFlash - 2P/3Al
49. 150mm - 500nm - TI - BiCMOS2 - BiCMOS - SOI, Comp, TFR - 1P/3Al
50. 150mm - 500nm - Tower - TS50 - CMOS - NA - 2P/3Al
51. 150mm - 500nm - TSMC - NA - CMOS - NA - 1P/3Al
52. 150mm - 500nm - UMC - NA - CMOS - NA - 1P/3Al
53. 150mm - 450nm - NXP - BiMOS3 - BiCMOS - NA - 1P/2Al
54. 150mm - 350nm - Tower - TS35 - CMOS - NA - 2P/4Al
55. 200mm - 800nm - Generic - NA - CMOS - NA - 1P/2Al
56. 200mm - 800nm - Generic - NA - CMOS - NA - 1P/3Al
57. 200mm - 800nm - Maxim - CB4 - BiCMOS - SOI, Comp, Schottky, TFR - 1P/3Au
58. 200mm - 700nm - Generic - NA - CMOS - NA - 1P/3Al
59. 200mm - 700nm - TI - LBC4 - BiCMOS - NA - 2P/3Al
60. 200mm - 600nm - Global Foundries (Sing) - NA - BiCMOS - NA - 2P/2Al
61. 200mm - 600nm - Global Foundries (Sing) - NA - BiCMOS - NA - 2P/3Al
62. 200mm - 600nm - Global Foundries (Sing) - NA - CMOS - Analog - 2P/2Al
63. 200mm - 600nm - Global Foundries (Sing) - NA - CMOS - NA - 1P/3Al
64. 200mm - 600nm - Global Foundries (Sing) - NA - EEPROM - NA - 2P/2Al
65. 200mm - 500nm - Freescale - NA - CMOS - DGO, eFlash - 2P/2Al
66. 200mm - 500nm - Generic - NA - BiCMOS - NA - 1P/3Al
67. 200mm - 500nm - Generic - NA - CMOS - NA - 1P/2Al
68. 200mm - 500nm - Generic - NA - CMOS - NA - 1P/3Al
69. 200mm - 500nm - Generic - NA - CMOS - NA - 1P/4Al
70. 200mm - 500nm - Global Foundries (Sing) - NA - CMOS - NA - 2P/3Al
71. 200mm - 500nm - Micronas - NA - CMOS - RF - 2P/2Al
72. 200mm - 500nm - TSMC - NA - CMOS - NA - 1P/3Al
73. 200mm - 500nm - UMC - NA - CMOS - NA - 1P/3Al
74. 200mm - 500nm - Vanguard - NA - CMOS - DNW, 1Vt - 1P/3Al
75. 200mm - 350nm - ASMC - NA - BiCMOS - EEPROM - 2P/3Al
76. 200mm - 350nm - ASMC - NA - CMOS - EEPROM - 2P/5Al
77. 200mm - 350nm - Freescale - SMOS7 - CMOS - NA - 1P/3Al
78. 200mm - 350nm - Generic - NA - BiCMOS - NA - 1P/5Al

79. 200mm - 350nm - Generic - NA - BiCMOS - NA - 1P/6AI
80. 200mm - 350nm - Generic - NA - CMOS - NA - 1P/3AI
81. 200mm - 350nm - Generic - NA - CMOS - NA - 1P/4AI
82. 200mm - 350nm - Generic - NA - CMOS - NA - 1P/5AI
83. 200mm - 350nm - Generic - NA - CMOS - NA - 1P/6AI
84. 200mm - 350nm - Global Foundries - 5PAe - SiGe - MIM, TaN res, TSV, DNW, DGO - 1P/4AI
85. 200mm - 350nm - Global Foundries (Sing) - NA - CMOS - DGO - 1P/3AI
86. 200mm - 350nm - Global Foundries (Sing) - NA - CMOS - DGO - 1P/4AI
87. 200mm - 350nm - Global Foundries (Sing) - NA - CMOS - DGO, Mixed Sig - 2P/4AI
88. 200mm - 350nm - Global Foundries (Sing) - NA - CMOS - NA - 1P/4AI
89. 200mm - 350nm - Hejian - NA - CMOS - eFlash - 2P/5AI
90. 200mm - 350nm - Intel - NA - BiCMOS - NA - 1P/4AI
91. 200mm - 350nm - Intel - NA - CMOS - NA - 1P/4AI
92. 200mm - 350nm - Microchip - CMOS - eFlash - 2P/3AI
93. 200mm - 350nm - NXP - NA - CMOS - eFlash - 2P/5AI
94. 200mm - 350nm - On Semi (AMI) - NA - CMOS - DMOS - 1P/3AI
95. 200mm - 350nm - Polar Fab - Polar 35 - BiCMOS - NA - 2P/2AI
96. 200mm - 350nm - Polar Fab - Polar 35 - BiCMOS - NA - 2P/3AI
97. 200mm - 350nm - SMIC - NA - CMOS - NA - 1P/4AI
98. 200mm - 350nm - STMicro - BiCMOS6G - BiCMOS - NA - 3P/5AI
99. 200mm - 350nm - TI - NA - CMOS - eFlash - 2P/3AI
100. 200mm - 350nm - TSMC - NA - CMOS - eFlash - 2P/3AI
101. 200mm - 350nm - TSMC - NA - CMOS - NA - 1P/4AI
102. 200mm - 350nm - UMC - NA - CMOS - NA - 1P/4AI
103. 200mm - 350nm - WaferTech - NA - CMOS - SRAM - 3P/4AI
104. 200mm - 350nm - X-Fab - NA - CMOS - LV, EEPROM, Schottky - 2P/4AI
105. 200mm - 350nm - X-Fab - NA - CMOS - Mixed Sig - 2P/4AI
106. 200mm - 300nm - Generic - NA - SRAM - NA - 2P/2AI
107. 200mm - 300nm - Generic - NA - SRAM - NA - 4P/2AI
108. 200mm - 250nm - Freescale - NA - CMOS - eFlash - 2P/3AI
109. 200mm - 250nm - Freescale - NA - CMOS - eFlash - 2P/4AI
110. 200mm - 250nm - Freescale - NA - CMOS - NA - 1P/4AI
111. 200mm - 250nm - Generic - NA - CMOS - RF - 1P/4AI
112. 200mm - 250nm - Generic - NA - SRAM - NA - 5P/3AI
113. 200mm - 250nm - Global Foundries (Sing) - NA - CMOS - DGO - 1P/5AI
114. 200mm - 250nm - Hejian - NA - CMOS - eFlash - 2P/5AI
115. 200mm - 250nm - Infineon - NA - SiGe - MIM - 2P/3AI
116. 200mm - 250nm - Intel - NA - CMOS - NA - 1P/5AI
117. 200mm - 250nm - Intel - ETOX VI - NOR - NA - 2P/2AI
118. 200mm - 250nm - Microchip - CMOS - eFlash - 2P/3AI
119. 200mm - 250nm - SMIC - NA - CMOS - DGO - 1P/5AI
120. 200mm - 250nm - STMicro - HCMOS7 - CMOS - NA - 1P/4AI
121. 200mm - 250nm - TSMC - NA - CMOS - NA - 1P/3AI
122. 200mm - 250nm - TSMC - NA - CMOS - DGO - 1P/4AI
123. 200mm - 250nm - TSMC - NA - CMOS - DGO, eFlash - 2P/4AI
124. 200mm - 250nm - TSMC - NA - CMOS - DGO - 1P/5AI
125. 200mm - 250nm - TSMC - NA - CMOS - NA - 1P/6AI

126. 200mm - 250nm - TSMC - STT - CMOS - NA - 1P/4Al
127. 200mm - 250nm - UMC - NA - CMOS - DGO - 1P/5Al
128. 200mm - 220nm - Infineon - NA - CMOS - DGO, eFlash - 2P/5Al
129. 200mm - 180nm - Freescale - NA - CMOS - DGO, eFlash - 1P/5Cu
130. 200mm - 180nm - Freescale - NA - CMOS - RF - 1P/4Cu
131. 200mm - 180nm - Freescale - NA - CMOS - SOI, DGO - 1P/7Al
132. 200mm - 180nm - Generic - NA - SRAM - NA - 5P/3Al
133. 200mm - 180nm - Global Foundries - 7HP - SiGe - MIM, TaN Res - 1P/6Cu
134. 200mm - 180nm - Global Foundries - 7RF - CMOS - RF, MIM, TaN Res - 1P/2Cu/2Al
135. 200mm - 180nm - Global Foundries - 7RF - CMOS - RF, MIM, TaN Res - 1P/3Cu/3Al
136. 200mm - 180nm - Global Foundries - 7RF SOI - CMOS - SOI, MIM, TaN Res - 1P/2Cu/1Al
137. 200mm - 180nm - Global Foundries - 7SF - CMOS - DGO - 1P/4Cu
138. 200mm - 180nm - Global Foundries - 7SF - CMOS - DGO - 1P/5Cu
139. 200mm - 180nm - Global Foundries - 7SF - CMOS - DGO - 1P/6Cu
140. 200mm - 180nm - Global Foundries - 7WL - SiGe - MIM, TaN Res - 1P/3Cu/3Al
141. 200mm - 180nm - Global Foundries - 7WL - SiGe - VNPN, HKMIM, TaN Res - 1P/3Cu/3Al
142. 200mm - 180nm - Global Foundries - NA - CMOS - eDRAM - 4P/5Cu
143. 200mm - 180nm - Global Foundries (Sing) - NA - CMOS - DGO - 1P/6Al
144. 200mm - 180nm - Global Foundries (Sing) - NA - CMOS - Mixed Sig, RF - 1P/6Al
145. 200mm - 180nm - Hejian - NA - CMOS - eFlash - 2P/5Al
146. 200mm - 180nm - Infineon - NA - CMOS - DGO, Fuse - 1P/4Cu/1Al
147. 200mm - 180nm - Infineon - B7HF200 - SiGe - MIM - 2P/4Cu
148. 200mm - 180nm - Intel - NA - CMOS - NA - 1P/6Al
149. 200mm - 180nm - Intel - ETOX VII - NOR - NA - 2P/3Al
150. 200mm - 180nm - NEC - NA - CMOS - DGO - 1P/5Al
151. 200mm - 180nm - NXP - NA - CMOS - DGO - 1P/1W/6Al
152. 200mm - 180nm - On Semi (AMI) - ONC18D - CMOS - DGO - 1P/5Al
153. 200mm - 180nm - On Semi (AMI) - ONC18D - CMOS - DGO - 1P/6Al
154. 200mm - 180nm - Renesas - NA - CMOS - eFlash - 2P/4Al
155. 200mm - 180nm - Samsung - LE18H - CMOS - EEPROM - 2P/4Al
156. 200mm - 180nm - Samsung - NA - SRAM - NA - 1P/4Al
157. 200mm - 180nm - SMIC - NA - CMOS - DGO - 1P/6Al
158. 200mm - 180nm - SSMC - NA - CMOS - DGO - 1P/6Al
159. 200mm - 180nm - STMicro - F8 - CMOS - EEPROM - 2P/4Al
160. 200mm - 180nm - STMicro - NA - EEPROM - EEPROM - 1P/2Al
161. 200mm - 180nm - TI - NA - CMOS - eFlash - 2P/4Al
162. 200mm - 180nm - TI - NA - CMOS - NA - 1P/5Al
163. 200mm - 180nm - TI - NA - CMOS - NA - 1P/5Cu
164. 200mm - 180nm - Toshiba - NA - CMOS - DGO - 1P/4Al
165. 200mm - 180nm - TowerJazz - CA18 - CMOS - DGO, RF - 1P/6Al
166. 200mm - 180nm - TowerJazz - CA18QG - CMOS - DGO, DNW, MIM, 4Vt - 1P/4Al
167. 200mm - 180nm - TowerJazz - CS18MT1 - CMOS - SOI, MIM, DNW, 2Vt - 1P/3Al
168. 200mm - 180nm - TowerJazz - CS18QT5 - CMOS - SOI, DNW, MIM, 2Vt - 1P/4Al
169. 200mm - 180nm - TowerJazz - SBC18H3 - SiGe - DGO - 1P/6Al
170. 200mm - 180nm - TowerJazz - TS18SL - CMOS - DGO - 1P/6Al
171. 200mm - 180nm - TSMC - HIP8NVM - CMOS - DGO, eFlash, MIM - 1P/5Al
172. 200mm - 180nm - TSMC - NA - CMOS - DGO - 1P/5Al
173. 200mm - 180nm - TSMC - NA - CMOS - DGO - 1P/6Al

174. 200mm - 180nm - TSMC - NA - CMOS - DGO, eFlash - 2P/4Al
175. 200mm - 180nm - TSMC - NA - CMOS - DGO, eFlash - 2P/6Al
176. 200mm - 180nm - TSMC - NA - CMOS - DGO, RF - 1P/4Al
177. 200mm - 180nm - UMC - NA - CMOS - DGO - 1P/5Al
178. 200mm - 180nm - UMC - NA - CMOS - DGO - 1P/6Al
179. 200mm - 180nm - Vanguard - NA - CMOS - DGO - 1P/4Al
180. 200mm - 160nm - SMIC - NA - CMOS - DGO - 1P/6Al
181. 200mm - 160nm - TowerJazz - NA - CMOS - DGO - 1P/5Al
182. 200mm - 152nm - TSMC - CM0152 - CMOS - DGO, MIM, DNW - 1P/4Al
183. 200mm - 150nm - Aptina - NA - ImgSen - FSI - 2P/3Al
184. 200mm - 150nm - Aptina - NA - ImgSen - FSI - 2P/5Al
185. 200mm - 150nm - Global Foundries - NA - CMOS - DGO - Fab 7 - 1P/7Cu
186. 200mm - 150nm - Numonyx - NA - NOR - NA - 2P/3Al
187. 200mm - 150nm - SMIC - NA - CMOS - DGO - 1P/7Cu
188. 200mm - 150nm - TSMC - NA - CMOS - DGO - 1P/5Cu/1Al
189. 200mm - 150nm - TSMC - NA - CMOS - DGO - 1P/6Cu
190. 200mm - 150nm - TSMC - NA - CMOS - DGO - 1P/7Cu
191. 200mm - 150nm - UMC - NA - CMOS - DGO - 1P/7Cu
192. 200mm - 150nm - UMC - NA - CMOS - DGO - 1P/8Al
193. 200mm - 140nm - SSMC - C14AMS-RF-EE - CMOS - EEPROM, RF - 3P/6Al
194. 200mm - 140nm - SSMC - CMOSNV14 - CMOS - NA - 1P/5Al
195. 200mm - 140nm - Toshiba - TC260 - DRAM - DGO, eDRAM - 4P/7Cu
196. 200mm - 130nm - Fujitsu - NA - CMOS - NA - 1P/8Cu/1Al
197. 200mm - 130nm - Global Foundries - 8HP - SiGe - MIM, TaN Res - 1P/6Cu
198. 200mm - 130nm - Global Foundries - 8HP - SiGe - MIM, TaN Res - 1P/7Cu
199. 200mm - 130nm - Global Foundries - 8HP - SiGe - MIM, TaN Res - 1P/8Cu/1Al
200. 200mm - 130nm - Global Foundries - 8RF - CMOS - MIM, TaN Res, RF - 1P/3Cu/1Al/1Cu/1Al
201. 200mm - 130nm - Global Foundries - 8SFG - CMOS - DGO - 1P/6Cu
202. 200mm - 130nm - Global Foundries - 8SFG - CMOS - DGO - 1P/7Cu
203. 200mm - 130nm - Global Foundries - 8SFG - CMOS - DGO - 1P/8Cu
204. 200mm - 130nm - Global Foundries - 9S - CMOS - DGO, Silk ILD - 1P/6Cu
205. 200mm - 130nm - Global Foundries - 9S - CMOS - DGO, Silk ILD - 1P/7Cu
206. 200mm - 130nm - Global Foundries - 9S - CMOS - DGO, Silk ILD - 1P/8Cu
207. 200mm - 130nm - Global Foundries - NA - CMOS - DGO - Fab 7 - 1P/8Cu
208. 200mm - 130nm - Hynix - NA - ImgSen - FSI - 1P/4Al
209. 200mm - 130nm - Infineon - NA - CMOS - eFlash - 2P/5Cu/1Al
210. 200mm - 130nm - Infineon - NA - CMOS - MIM, RF - 1P/4Cu/2Al
211. 200mm - 130nm - Infineon - NA - SiGe - MIM - 2P/5Cu
212. 200mm - 130nm - Intel - NA - CMOS - NA - 1P/6Cu
213. 200mm - 130nm - Numonyx - NA - NOR - NA - 2P/3Al
214. 200mm - 130nm - Samsung - LE13 - CMOS - EEPROM - 2P/4Cu
215. 200mm - 130nm - SMIC - NA - CMOS - DGO - 1P/8Cu
216. 200mm - 130nm - STMicro - BiCMOS9 - BiCMOS - SiGe, MIM - 1P/7Cu
217. 200mm - 130nm - STMicro - BiCMOS9 - BiCMOS - SiGe - 1P/7Cu
218. 200mm - 130nm - STMicro - F9 - CMOS - EEPROM - 2P/4Al
219. 200mm - 130nm - STMicro - HCMOS9A - CMOS - NA - 1P/4Cu/1Al
220. 200mm - 130nm - STMicro - HCMOS9SOI - CMOS - NA - 1P/4Cu

221. 200mm - 130nm - TI - NA - CMOS - NA - 1P/5Cu
222. 200mm - 130nm - TI - NA - CMOS - NA - 1P/5Cu/1Al
223. 200mm - 130nm - TI - NA - CMOS - NA - 1P/6Cu/1Al
224. 200mm - 130nm - TowerJazz - NA - BiCMOS - TGO, SiGe, MIM, TFR - Fab 3 - 1P/6Al
225. 200mm - 130nm - TowerJazz - TS13SL - CMOS - DGO - Fab 2 - 1P/6Cu
226. 200mm - 130nm - TowerJazz - TS13SL - CMOS - DGO - Fab 2 - 1P/7Cu
227. 200mm - 130nm - TowerJazz - TS13SL - CMOS - DGO - Fab 2 - 1P/8Cu
228. 200mm - 130nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/6Cu
229. 200mm - 130nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/6Cu/1Al
230. 200mm - 130nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/7Cu
231. 200mm - 130nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/8Cu
232. 200mm - 130nm - UMC - L130 - CMOS - DGO, 2Vt - 1P/6Cu
233. 200mm - 130nm - UMC - L130 - CMOS - DGO, 2Vt - 1P/6Cu/1Al
234. 200mm - 130nm - UMC - L130 - CMOS - DGO, 2Vt - 1P/7Cu
235. 200mm - 130nm - UMC - L130 - CMOS - DGO, 2Vt - 1P/8Cu
236. 200mm - 120nm - Samsung - NA - SRAM - NA - 1P/4Cu
237. 200mm - 110nm - Aptina - NA - ImgSen - FSI - 1P/5Al
238. 200mm - 110nm - Numonyx - NA - NOR - NA - 2P/3Al
239. 200mm - 110nm - Toshiba - TC280 - CMOS - DGO, eDRAM - 4P/7Cu
240. 200mm - 110nm - TSMC - NA - CMOS - DGO - 1P/6Cu
241. 200mm - 110nm - TSMC - NA - CMOS - DGO - 1P/7Cu
242. 200mm - 110nm - TSMC - NA - CMOS - DGO - 1P/8Cu
243. 200mm - 110nm - TSMC - NA - NOR - NA - 2P/3Cu
244. 200mm - 110nm - UMC - NA - CMOS - DGO - 1P/6Cu
245. 200mm - 90nm - Aptina - NA - ImgSen - FSI - 1P/4Cu/1Al
246. 200mm - 90nm - Dongbu Hitek - NA - NOR - NA - 2P/2Al
247. 200mm - 90nm - Freescale - NA - CMOS - DGO, eFlash - 2P/6Cu
248. 200mm - 90nm - Freescale - NA - CMOS - SOI, TGO - 1P/6Cu
249. 200mm - 90nm - Freescale - NA - CMOS - SOI, TGO - 1P/7Cu
250. 200mm - 90nm - Infineon - NA - CMOS - DGO, Flash - 1P/4Cu/1Al
251. 200mm - 90nm - Intel - ETOX IX - NOR - NA - 2P/3Cu/1Al
252. 200mm - 90nm - Samsung - NA - ImgSen - BSI - 1P/4Cu/1Al
253. 200mm - 90nm - Samsung - NA - ImgSen - FSI - 1P/4Cu/1Al
254. 200mm - 90nm - Samsung - NA - NOR - NA - 2P/1W/2Al
255. 200mm - 90nm - Spansion - NA - NOR - NA - 2P/1W/2Al
256. 200mm - 90nm - STMicro - NA - CMOS - NA - 1P/6Cu
257. 200mm - 90nm - STMicro - NA - CMOS - DGO - 1P/7Cu
258. 200mm - 65nm - Numonyx - NA - NOR - NA - 2P/1W/2Al
259. 300mm - 180nm - SMIC - NA - CMOS - DGO - 1P/6Al
260. 300mm - 150nm - Global Foundries - NA - CMOS - DGO - Fab 7 - 1P/6Cu
261. 300mm - 150nm - Global Foundries - NA - CMOS - DGO - Fab 7 - 1P/7Cu
262. 300mm - 150nm - Samsung - NA - DRAM - NA - 4P/1W/2Al
263. 300mm - 150nm - SMIC - NA - CMOS - DGO - 1P/6Cu
264. 300mm - 150nm - SMIC - NA - CMOS - DGO - 1P/7Cu
265. 300mm - 150nm - TSMC - NA - CMOS - DGO - 1P/6Cu
266. 300mm - 150nm - TSMC - NA - CMOS - DGO - 1P/7Cu
267. 300mm - 150nm - UMC - NA - CMOS - DGO - 1P/6Cu
268. 300mm - 150nm - UMC - NA - CMOS - DGO - 1P/7Cu

269. 300mm - 130nm - Global Foundries - 8HP - SiGe - MIM, TaN Res - 1P/6Cu
270. 300mm - 130nm - Global Foundries - 8HP - SiGe - MIM, TaN Res - 1P/7Cu
271. 300mm - 130nm - Global Foundries - 8HP - SiGe - MIM, TaN Res - 1P/8Cu
272. 300mm - 130nm - Global Foundries - 8RF - CMOS - MIM, TaN Res, RF - 1P/3Cu/1Al/1Cu/1Al
273. 300mm - 130nm - Global Foundries - 8SFG - CMOS - DGO - 1P/6Cu
274. 300mm - 130nm - Global Foundries - 8SFG - CMOS - DGO - 1P/7Cu
275. 300mm - 130nm - Global Foundries - 8SFG - CMOS - DGO - 1P/8Cu
276. 300mm - 130nm - Global Foundries - 9S - CMOS - DGO, Silk ILD - 1P/6Cu
277. 300mm - 130nm - Global Foundries - 9S - CMOS - DGO, Silk ILD - 1P/7Cu
278. 300mm - 130nm - Global Foundries - 9S - CMOS - DGO, Silk ILD - 1P/8Cu
279. 300mm - 130nm - Global Foundries - NA - CMOS - DGO - Fab 7 - 1P/6Cu
280. 300mm - 130nm - Global Foundries - NA - CMOS - DGO - Fab 7 - 1P/7Cu
281. 300mm - 130nm - Global Foundries - NA - CMOS - DGO - Fab 7 - 1P/8Cu
282. 300mm - 130nm - Global Foundries - UltraCMOS 11 - CMOS - DGO, SOI - Fab 7 - 1P/4Cu/1Al
283. 300mm - 130nm - Intel - Px60 - CMOS - NA - 1P/6Cu
284. 300mm - 130nm - Renesas - NA - CMOS - DGO - 1P/1W/5Cu/1Al
285. 300mm - 130nm - Samsung - NA - DRAM - NA - 4P/1W/2Al
286. 300mm - 130nm - SMIC - NA - CMOS - DGO - 1P/6Cu
287. 300mm - 130nm - SMIC - NA - CMOS - DGO - 1P/7Cu
288. 300mm - 130nm - SMIC - NA - CMOS - DGO - 1P/8Cu
289. 300mm - 130nm - STMicro - NA - CMOS - DGO - 1P/6Cu
290. 300mm - 130nm - STMicro - NA - CMOS - DGO - 1P/7Cu
291. 300mm - 130nm - STMicro - NA - CMOS - DGO - 1P/8Cu
292. 300mm - 130nm - TI - NA - CMOS - NA - 1P/5Cu
293. 300mm - 130nm - TI - NA - CMOS - NA - 1P/5Cu/1Al
294. 300mm - 130nm - TI - NA - CMOS - NA - 1P/6Cu
295. 300mm - 130nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/6Cu
296. 300mm - 130nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/7Cu
297. 300mm - 130nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/8Cu
298. 300mm - 130nm - UMC - L130 - CMOS - DGO, 2Vt - 1P/6Cu
299. 300mm - 130nm - UMC - L130 - CMOS - DGO, 2Vt - 1P/7Cu
300. 300mm - 130nm - UMC - L130 - CMOS - DGO, 2Vt - 1P/8Cu
301. 300mm - 120nm - Samsung - NA - NAND - NA - 4P/1W/1Al
302. 300mm - 120nm - SK Hynix - NA - DRAM - NA - M10 - 5P/1W/2Al
303. 300mm - 110nm - Micron - NA - DRAM - NA - 5P/1W/2Cu
304. 300mm - 110nm - Samsung - NA - DRAM - NA - 4P/1W/2Al
305. 300mm - 110nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/6Cu
306. 300mm - 110nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/7Cu
307. 300mm - 110nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/8Cu
308. 300mm - 95nm - Micron - NA - DRAM - NA - 4P/1W/2Cu
309. 300mm - 90nm - Global Foundries - 9RF - CMOS - VNPN, HKMIM, TaN Res - 1P/3Cu/3Al
310. 300mm - 90nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/7Cu
311. 300mm - 90nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/8Cu
312. 300mm - 90nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/9Cu
313. 300mm - 90nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/10Cu
314. 300mm - 90nm - Intel - P1262 - CMOS - NA - 1P/7Cu

315. 300mm - 90nm - Intel - P1263 - SiGe - NA - 1P/7Cu
316. 300mm - 90nm - Samsung - NA - CMOS - DGO, CPA - 1P/7Cu
317. 300mm - 90nm - Samsung - NA - CMOS - DGO, CPA - 1P/8Cu
318. 300mm - 90nm - Samsung - NA - CMOS - DGO, CPA - 1P/9Cu
319. 300mm - 90nm - Samsung - NA - CMOS - DGO, CPA - 1P/10Cu
320. 300mm - 90nm - Samsung - NA - DRAM - NA - 5P/1W/2Al
321. 300mm - 90nm - Samsung - NA - NAND - NA - 4P/1W/1Al
322. 300mm - 90nm - SMIC - LL - CMOS - DGO, Res, 2Vt - 1P/6Cu
323. 300mm - 90nm - SMIC - NA - CMOS - DGO - 1P/6Cu
324. 300mm - 90nm - SMIC - NA - CMOS - DGO - 1P/7Cu
325. 300mm - 90nm - SMIC - NA - CMOS - DGO - 1P/8Cu
326. 300mm - 90nm - SMIC - NA - CMOS - DGO - 1P/9Cu
327. 300mm - 90nm - SMIC - NA - NOR - NA - 1P/1W/2Al
328. 300mm - 90nm - Sony - NA - CMOS - eDRAM - 1P/5Cu/1Al
329. 300mm - 90nm - Sony - NA - CMOS - eDRAM - 1P/11Cu
330. 300mm - 90nm - Sony - NA - ImgSen - BSI - 1P/5Cu
331. 300mm - 90nm - Sony - NA - ImgSen - FSI - 1P/5Cu
332. 300mm - 90nm - STMicro - NA - CMOS - NA - 1P/6Cu
333. 300mm - 90nm - STMicro - NA - CMOS - DGO - 1P/7Cu
334. 300mm - 90nm - STMicro - NA - CMOS - DGO - 1P/8Cu
335. 300mm - 90nm - STMicro - NA - CMOS - DGO - 1P/9Cu
336. 300mm - 90nm - TI - NA - CMOS - DGO - 1P/5Cu/1Al
337. 300mm - 90nm - TI - NA - CMOS - DGO - 1P/6Cu
338. 300mm - 90nm - TI - NA - CMOS - DGO - 1P/6Cu/1Al
339. 300mm - 90nm - TI - NA - CMOS - DGO - 1P/9Cu
340. 300mm - 90nm - Toshiba - NA - NAND - NA - 3P/1W/2Al
341. 300mm - 90nm - TSMC - LP - CMOS - DGO, Res, 2Vt - 1P/6Cu
342. 300mm - 90nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/6Cu
343. 300mm - 90nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/7Cu
344. 300mm - 90nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/8Cu
345. 300mm - 90nm - TSMC - NA - CMOS - DGO, 2Vt - 1P/9Cu
346. 300mm - 90nm - TSMC - NA - ImgSen - BSI - 1P/4Cu
347. 300mm - 90nm - UMC - L90 - CMOS - DGO, 2Vt - 12A - 1P/6Cu
348. 300mm - 90nm - UMC - L90 - CMOS - DGO, 2Vt - 12A - 1P/7Cu
349. 300mm - 90nm - UMC - L90 - CMOS - DGO, 2Vt - 12A - 1P/8Cu
350. 300mm - 90nm - UMC - L90 - CMOS - DGO, 2Vt - 12A - 1P/9Cu
351. 300mm - 90nm - UMC - LL - CMOS - DGO, Res, 2Vt - 12i - 1P/6Cu
352. 300mm - 80nm - Samsung - NA - DRAM - NA - 5P/1W/2Al
353. 300mm - 80nm - SK Hynix - NA - DRAM - NA - M10 - 5P/1W/2Al
354. 300mm - 78nm - Micron - NA - DRAM - NA - 4P/1W/2Cu
355. 300mm - 75nm - Macronix - NA - NOR - NA - 2P/3Al
356. 300mm - 75nm - Samsung - NA - NAND - NA - 3P/2W/2Al
357. 300mm - 70nm - Toshiba - NA - NAND - NA - 3P/1W/2Al
358. 300mm - 68nm - Micron - NA - DRAM - NA - Fab 6 - 4P/1W/2Cu
359. 300mm - 68nm - Micron - NA - DRAM - NA - Fab 16 - 4P/1W/2Cu
360. 300mm - 68nm - Samsung - NA - DRAM - NA - 5P/1W/2Al
361. 300mm - 66nm - SK Hynix - NA - DRAM - NA - M10 - 5P/1W/2Al
362. 300mm - 65nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/7Cu

363. 300mm - 65nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/8Cu
364. 300mm - 65nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/9Cu
365. 300mm - 65nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/10Cu
366. 300mm - 65nm - Intel - P1264 - CMOS - NA - 1P/8Cu
367. 300mm - 65nm - Renesas - NA - CMOS - DGO - 1P/6Cu/1Al
368. 300mm - 65nm - Samsung - NA - CMOS - DGO, CPA - 1P/7Cu
369. 300mm - 65nm - Samsung - NA - CMOS - DGO, CPA - 1P/8Cu
370. 300mm - 65nm - Samsung - NA - CMOS - DGO, CPA - 1P/9Cu
371. 300mm - 65nm - Samsung - NA - CMOS - DGO, CPA - 1P/10Cu
372. 300mm - 65nm - Samsung - NA - InterPos - NA - 1P/3Cu
373. 300mm - 65nm - Samsung - NA - InterPos - NA - 1P/4Cu
374. 300mm - 65nm - Samsung - NA - NAND - NA - 3P/2W/2Al
375. 300mm - 65nm - SMIC - NA - CMOS - DGO - 1P/6Cu
376. 300mm - 65nm - SMIC - NA - CMOS - DGO - 1P/7Cu
377. 300mm - 65nm - SMIC - NA - CMOS - DGO - 1P/8Cu
378. 300mm - 65nm - SMIC - NA - CMOS - DGO - 1P/9Cu
379. 300mm - 65nm - SMIC - NA - CMOS - DGO - 1P/10Cu
380. 300mm - 65nm - Sony - NA - lmgSen - BSI - 1P/5Cu
381. 300mm - 65nm - Sony - NA - lmgSen - FSI - 1P/5Cu
382. 300mm - 65nm - STMicro - NA - CMOS - DGO - 1P/8Cu
383. 300mm - 65nm - STMicro - NA - CMOS - DGO - 1P/9Cu
384. 300mm - 65nm - STMicro - NA - CMOS - DGO - 1P/10Cu
385. 300mm - 65nm - TI - NA - CMOS - DGO - 1P/6Cu/1Al
386. 300mm - 65nm - TI - NA - CMOS - DGO - 1P/7Cu/1Al
387. 300mm - 65nm - Toshiba - NA - BSI - NA - 1P/5Cu/1Al
388. 300mm - 65nm - TSMC - LP - CMOS - DGO, Res, 2Vt - 1P/6Cu
389. 300mm - 65nm - TSMC - NA - BSI - NA - 1P/4Cu/1Al
390. 300mm - 65nm - TSMC - NA - CMOS - DGO, 3Vt - 1P/6Cu
391. 300mm - 65nm - TSMC - NA - CMOS - DGO, 3Vt - 1P/7Cu
392. 300mm - 65nm - TSMC - NA - CMOS - DGO, 3Vt - 1P/8Cu
393. 300mm - 65nm - TSMC - NA - CMOS - DGO, 3Vt - 1P/9Cu
394. 300mm - 65nm - TSMC - NA - CMOS - DGO, 3Vt - 1P/10Cu
395. 300mm - 65nm - TSMC - NA - InterPos - NA - 1P/4Cu
396. 300mm - 65nm - TSMC - ULP - CMOS - DGO, Res, 2Vt - 1P/6Cu
397. 300mm - 65nm - UMC - LP - CMOS - DGO, Res, 2Vt - 12i - 1P/6Cu
398. 300mm - 65nm - UMC - NA - CMOS - DGO, 3Vt - 12A - 1P/6Cu
399. 300mm - 65nm - UMC - NA - CMOS - DGO, 3Vt - 12A - 1P/7Cu
400. 300mm - 65nm - UMC - NA - CMOS - DGO, 3Vt - 12A - 1P/8Cu
401. 300mm - 65nm - UMC - NA - CMOS - DGO, 3Vt - 12A - 1P/9Cu
402. 300mm - 65nm - UMC - NA - CMOS - DGO, 3Vt - 12A - 1P/10Cu
403. 300mm - 65nm - UMC - NA - InterPos - NA - 12A - 1P/4Cu
404. 300mm - 60nm - TSMC - NA - CMOS - DGO, 3Vt - 1P/7Cu
405. 300mm - 60nm - TSMC - NA - CMOS - DGO, 3Vt - 1P/8Cu
406. 300mm - 60nm - TSMC - NA - CMOS - DGO, 3Vt - 1P/9Cu
407. 300mm - 60nm - TSMC - NA - CMOS - DGO, 3Vt - 1P/10Cu
408. 300mm - 58nm - Micron - NA - DRAM - NA - 1P/1W/2Cu/1Al
409. 300mm - 58nm - Samsung - NA - DRAM - NA - 4P/1W/2Cu/1Al
410. 300mm - 58nm - Winbond - NA - NOR - NA - 2P/3Al

411. 300mm - 56nm - Toshiba - NA - NAND - NA - 3P/1W/1Cu/1Al
412. 300mm - 55nm - Macronix - NA - NOR - NA - 2P/3Al
413. 300mm - 55nm - SMIC - LP - CMOS - DGO, Res, HDSRAM, 3Vt - 1P/6Cu
414. 300mm - 55nm - STMicro - B55 - BiCMOS - DGO, SiGe HBT, MIM - 1P/8Cu
415. 300mm - 55nm - STMicro - NA - CMOS - DGO - 1P/7Cu
416. 300mm - 55nm - STMicro - NA - CMOS - DGO - 1P/8Cu
417. 300mm - 55nm - STMicro - NA - CMOS - DGO - 1P/9Cu
418. 300mm - 55nm - STMicro - NA - CMOS - DGO - 1P/10Cu
419. 300mm - 55nm - TSMC - G - CMOS - DGO, 3Vt - 1P/6Cu
420. 300mm - 55nm - TSMC - G - CMOS - DGO, 3Vt - 1P/7Cu
421. 300mm - 55nm - TSMC - G - CMOS - DGO, 3Vt - 1P/8Cu
422. 300mm - 55nm - TSMC - G - CMOS - DGO, 3Vt - 1P/9Cu
423. 300mm - 55nm - TSMC - G - CMOS - DGO, 3Vt - 1P/10Cu
424. 300mm - 55nm - UMC - NA - CMOS - DGO, 3Vt - 12A - 1P/6Cu
425. 300mm - 55nm - UMC - NA - CMOS - DGO, 3Vt - 12i - 1P/6Cu
426. 300mm - 55nm - UMC - NA - CMOS - DGO, 3Vt - 12A - 1P/7Cu
427. 300mm - 55nm - UMC - NA - CMOS - DGO, 3Vt - 12i - 1P/7Cu
428. 300mm - 55nm - UMC - NA - CMOS - DGO, 3Vt - 12A - 1P/8Cu
429. 300mm - 55nm - UMC - NA - CMOS - DGO, 3Vt - 12i - 1P/8Cu
430. 300mm - 55nm - UMC - NA - CMOS - DGO, 3Vt - 12A - 1P/9Cu
431. 300mm - 55nm - UMC - NA - CMOS - DGO, 3Vt - 12i - 1P/9Cu
432. 300mm - 55nm - UMC - NA - CMOS - DGO, 3Vt - 12A - 1P/10Cu
433. 300mm - 55nm - UMC - NA - CMOS - DGO, 3Vt - 12i - 1P/10Cu
434. 300mm - 54nm - SK Hynix - NA - DRAM - NA - M10 - 5P/1W/3Al
435. 300mm - 51nm - Samsung - NA - NAND - NA - 3P/2W/2Al
436. 300mm - 50nm - Micron - NA - DRAM - NA - Fab 6 - 2P/1W/2Cu/1Al
437. 300mm - 50nm - Micron - NA - DRAM - NA - Fab 16 - 2P/1W/2Cu/1Al
438. 300mm - 48nm - Samsung - NA - DRAM - NA - 4P/1W/2Al
439. 300mm - 46nm - Winbond - NA - SRAM - NA - 1P/2Al
440. 300mm - 45nm - Intel - P1266 - CMOS - HKMG - 1P/9Cu
441. 300mm - 45nm - Samsung - NA - CMOS - DGO, CPA - 1P/8Cu
442. 300mm - 45nm - Samsung - NA - CMOS - DGO, CPA - 1P/9Cu
443. 300mm - 45nm - Samsung - NA - CMOS - DGO, CPA - 1P/10Cu
444. 300mm - 45nm - Samsung - NA - CMOS - DGO, CPA - 1P/11Cu
445. 300mm - 45nm - Samsung - VNAND - NAND - 24L 3D - 1W/1Cu/1Al
446. 300mm - 45nm - STMicro - NA - CMOS - DGO - 1P/8Cu
447. 300mm - 45nm - STMicro - NA - CMOS - DGO - 1P/9Cu
448. 300mm - 45nm - STMicro - NA - CMOS - DGO - 1P/10Cu
449. 300mm - 45nm - Toshiba - NA - CMOS - DGO - 1P/10Cu
450. 300mm - 44nm - SK Hynix - NA - DRAM - NA - M10 - 1P/1W/1Cu/1Al
451. 300mm - 43nm - Toshiba - NA - NAND - NA - 3P/1W/1Cu/1Al
452. 300mm - 42nm - Micron - NA - DRAM - NA - Fab 6 - 1P/1W/2Cu
453. 300mm - 42nm - Micron - NA - DRAM - NA - Fab 16 - 1P/1W/2Cu
454. 300mm - 42nm - Samsung - NA - NAND - NA - 3P/1W/1Cu/1Al
455. 300mm - 40nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 1 - 1P/8Cu
456. 300mm - 40nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 1 - 1P/9Cu
457. 300mm - 40nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 1 - 1P/10Cu
458. 300mm - 40nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 1 - 1P/11Cu

459. 300mm - 40nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/8Cu
460. 300mm - 40nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/9Cu
461. 300mm - 40nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/10Cu
462. 300mm - 40nm - Global Foundries - NA - CMOS - DGO, CPA - Fab 7 - 1P/11Cu
463. 300mm - 40nm - Renesas - CB40-LR - CMOS - DGO - 1P/7Cu
464. 300mm - 40nm - Renesas - CB40-LR - CMOS - DGO, eDRAM - 1P/7Cu
465. 300mm - 40nm - Samsung - VNAND - NAND - 32L 3D - 1W/1Cu/1Al
466. 300mm - 40nm - SMIC - LL - CMOS - DGO - 1P/9Cu
467. 300mm - 40nm - SMIC - LL - CMOS - DGO - 1P/10Cu
468. 300mm - 40nm - SMIC - LL - CMOS - DGO - 1P/11Cu
469. 300mm - 40nm - STMicro - NA - CMOS - DGO, 3Vt - 1P/5Cu/1Al
470. 300mm - 40nm - Toshiba - NA - CMOS - FPGA, eFlash - 1P/11Cu
471. 300mm - 40nm - Toshiba - NA - CMOS - NA - 1P/8Cu
472. 300mm - 40nm - TSMC - NA - BSI - DGO - 1P/4Cu/1Al
473. 300mm - 40nm - TSMC - G - CMOS - DGO, 4Vt - 1P/7Cu
474. 300mm - 40nm - TSMC - G - CMOS - DGO, 4Vt - 1P/8Cu
475. 300mm - 40nm - TSMC - G - CMOS - DGO, 4Vt - 1P/9Cu
476. 300mm - 40nm - TSMC - G - CMOS - DGO, 4Vt - 1P/10Cu
477. 300mm - 40nm - TSMC - G - CMOS - DGO, 4Vt - 1P/11Cu
478. 300mm - 40nm - TSMC - LP - CMOS - DGO, 2Vt - 1P/6Cu
479. 300mm - 40nm - TSMC - LP - CMOS - DGO, Res, 2Vt - 1P/6Cu
480. 300mm - 40nm - TSMC - LP - CMOS - DGO, Res, 2Vt - 1P/7Cu
481. 300mm - 40nm - TSMC - LP (simplified) - CMOS - DGO, Res, HDSRAM, 4Vt - 1P/7Cu
482. 300mm - 40nm - TSMC - LP - CMOS - DGO, 3Vt - 1P/7Cu
483. 300mm - 40nm - TSMC - LP - CMOS - DGO, 3Vt - 1P/8Cu
484. 300mm - 40nm - TSMC - LP - CMOS - DGO, 3Vt - 1P/9Cu
485. 300mm - 40nm - TSMC - LP - CMOS - DGO, 3Vt - 1P/10Cu
486. 300mm - 40nm - TSMC - LP - CMOS - DGO, 3Vt - 1P/11Cu
487. 300mm - 40nm - TSMC - LPG - CMOS - TGO - 1P/9Cu
488. 300mm - 40nm - TSMC - LPG - CMOS - TGO - 1P/10Cu
489. 300mm - 40nm - TSMC - LPG - CMOS - TGO - 1P/11Cu
490. 300mm - 40nm - TSMC - NA - CMOS - FPGA, eFlash - 1P/9Cu
491. 300mm - 40nm - TSMC - NA - CMOS - FPGA, eFlash - 1P/10Cu
492. 300mm - 40nm - TSMC - NA - CMOS - FPGA, eFlash - 1P/11Cu
493. 300mm - 40nm - UMC - G - CMOS - DGO - 12A - 1P/7Cu
494. 300mm - 40nm - UMC - G - CMOS - DGO - 12A - 1P/8Cu
495. 300mm - 40nm - UMC - G - CMOS - DGO - 12A - 1P/9Cu
496. 300mm - 40nm - UMC - G - CMOS - DGO - 12A - 1P/10Cu
497. 300mm - 40nm - UMC - G - CMOS - DGO - 12A - 1P/11Cu
498. 300mm - 40nm - UMC - LP - CMOS - DGO, Res, 2Vt - 12i - 1P/6Cu
499. 300mm - 40nm - UMC - LP - CMOS - DGO, Res, 3Vt - 12i - 1P/7Cu
500. 300mm - 40nm - UMC - LP - CMOS - DGO - 12A - 1P/7Cu
501. 300mm - 40nm - UMC - LP - CMOS - DGO - 12A - 1P/8Cu
502. 300mm - 40nm - UMC - LP - CMOS - DGO - 12A - 1P/9Cu
503. 300mm - 40nm - UMC - LP - CMOS - DGO - 12A - 1P/10Cu
504. 300mm - 40nm - UMC - LP - CMOS - DGO - 12A - 1P/11Cu
505. 300mm - 40nm - UMC - NA - CMOS - FPGA, eFlash - 1P/11Cu
506. 300mm - 35nm - Samsung - NA - NAND - NA - 3P/1W/1Cu/1Al

507. 300mm - 32nm - Intel - P1268 - CMOS - HKMG - 1P/9Cu
508. 300mm - 32nm - Intel - P1269 - CMOS - DGO, HKMG, MIM, Res - 1P/10Cu
509. 300mm - 32nm - Samsung - NA - CMOS - DGO, HKMG, CPA - 1P/9Cu
510. 300mm - 32nm - Samsung - NA - CMOS - DGO, HKMG, CPA - 1P/10Cu
511. 300mm - 32nm - Samsung - NA - CMOS - DGO, HKMG, CPA - 1P/11Cu
512. 300mm - 32nm - Samsung - NA - DRAM - NA - 4P/1W/2Cu/1Al
513. 300mm - 32nm - Toshiba - NA - NAND - NA - 3P/1W/1Cu/1Al
514. 300mm - 31nm - Micron - NA - DRAM - NA - Fab 6 - 2P/1W/2Cu/1Al
515. 300mm - 31nm - Micron - NA - DRAM - NA - Fab 16 - 2P/1W/2Cu/1Al
516. 300mm - 30nm - SK Hynix - NA - DRAM - NA - M10 - 5P/1W/1Cu/1Al
517. 300mm - 28nm - Global Foundries - HPP - CMOS - DGO, CPA, HKMG - 1P/9Cu
518. 300mm - 28nm - Global Foundries - HPP - CMOS - DGO, CPA, HKMG - 1P/10Cu
519. 300mm - 28nm - Global Foundries - HPP - CMOS - DGO, CPA, HKMG - 1P/11Cu
520. 300mm - 28nm - Samsung - FD-SOI - CMOS - DGO, CPA, HKMG - 1P/9Cu
521. 300mm - 28nm - Samsung - FD-SOI - CMOS - DGO, CPA, HKMG - 1P/10Cu
522. 300mm - 28nm - Samsung - FD-SOI - CMOS - DGO, CPA, HKMG - 1P/11Cu
523. 300mm - 28nm - Samsung - LPH (G) - CMOS - DGO, CPA, HKMG - 1P/9Cu
524. 300mm - 28nm - Samsung - LPH (G) - CMOS - DGO, CPA, HKMG - 1P/10Cu
525. 300mm - 28nm - Samsung - LPH (G) - CMOS - DGO, CPA, HKMG - 1P/11Cu
526. 300mm - 28nm - Samsung - LPP - CMOS - DGO, CPA, HKMG - 1P/9Cu
527. 300mm - 28nm - Samsung - LPP - CMOS - DGO, CPA, HKMG - 1P/10Cu
528. 300mm - 28nm - Samsung - LPP - CMOS - DGO, CPA, HKMG - 1P/11Cu
529. 300mm - 28nm - Samsung - LPS - CMOS - DGO, CPA - 1P/9Cu
530. 300mm - 28nm - Samsung - LPS - CMOS - DGO, CPA - 1P/10Cu
531. 300mm - 28nm - Samsung - LPS - CMOS - DGO, CPA - 1P/11Cu
532. 300mm - 28nm - SMIC - HK - CMOS - DGO, CPA - 1P/9Cu
533. 300mm - 28nm - SMIC - HK - CMOS - DGO, CPA - 1P/10Cu
534. 300mm - 28nm - SMIC - HK - CMOS - DGO, CPA - 1P/11Cu
535. 300mm - 28nm - SMIC - PS - CMOS - DGO, CPA - 1P/9Cu
536. 300mm - 28nm - SMIC - PS - CMOS - DGO, CPA - 1P/10Cu
537. 300mm - 28nm - SMIC - PS - CMOS - DGO, CPA - 1P/11Cu
538. 300mm - 28nm - STMicro - FD-SOI - CMOS - DGO, CPA, HKMG - 1P/9Cu
539. 300mm - 28nm - STMicro - FD-SOI - CMOS - DGO, CPA, HKMG - 1P/10Cu
540. 300mm - 28nm - STMicro - FD-SOI - CMOS - DGO, CPA, HKMG - 1P/11Cu
541. 300mm - 28nm - STMicro - LP - CMOS - DGO, CPA, HKMG - 1P/9Cu
542. 300mm - 28nm - STMicro - LP - CMOS - DGO, CPA, HKMG - 1P/10Cu
543. 300mm - 28nm - STMicro - LP - CMOS - DGO, CPA, HKMG - 1P/11Cu
544. 300mm - 28nm - TSMC - HP (G) - CMOS - DGO, HKMG, 4Vt - 1P/7Cu
545. 300mm - 28nm - TSMC - HP (G) - CMOS - DGO, HKMG, 4Vt - 1P/8Cu
546. 300mm - 28nm - TSMC - HP (G) - CMOS - DGO, HKMG, 4Vt - 1P/9Cu
547. 300mm - 28nm - TSMC - HP (G) - CMOS - DGO, HKMG, 4Vt - 1P/10Cu
548. 300mm - 28nm - TSMC - HP (G) - CMOS - DGO, HKMG, 4Vt - 1P/11Cu
549. 300mm - 28nm - TSMC - HPC - CMOS - DGO, HKMG, Res, 2Vt - 1P/7Cu
550. 300mm - 28nm - TSMC - HPC - CMOS - DGO, HKMG, Res, 4Vt - 1P/8Cu
551. 300mm - 28nm - TSMC - HPC - CMOS - DGO, HKMG, Res, 4Vt - 1P/9Cu
552. 300mm - 28nm - TSMC - HPC - CMOS - DGO, HKMG, 5Vt - 1P/7Cu
553. 300mm - 28nm - TSMC - HPC - CMOS - DGO, HKMG, 5Vt - 1P/8Cu
554. 300mm - 28nm - TSMC - HPC - CMOS - DGO, HKMG, 5Vt - 1P/9Cu

555. 300mm - 28nm - TSMC - HPC - CMOS - DGO, HKMG, 5Vt - 1P/10Cu
556. 300mm - 28nm - TSMC - HPC - CMOS - DGO, HKMG, 5Vt - 1P/11Cu
557. 300mm - 28nm - TSMC - HPL - CMOS - DGO, HKMG, 4Vt - 1P/7Cu
558. 300mm - 28nm - TSMC - HPL - CMOS - DGO, HKMG, 4Vt - 1P/8Cu
559. 300mm - 28nm - TSMC - HPL - CMOS - DGO, HKMG, 4Vt - 1P/9Cu
560. 300mm - 28nm - TSMC - HPL - CMOS - DGO, HKMG, 4Vt - 1P/10Cu
561. 300mm - 28nm - TSMC - HPL - CMOS - DGO, HKMG, 4Vt - 1P/11Cu
562. 300mm - 28nm - TSMC - HPM - CMOS - TGO, HKMG, 5Vt - 1P/7Cu
563. 300mm - 28nm - TSMC - HPM - CMOS - TGO, HKMG, 5Vt - 1P/8Cu
564. 300mm - 28nm - TSMC - HPM - CMOS - TGO, HKMG, 5Vt - 1P/9Cu
565. 300mm - 28nm - TSMC - HPM - CMOS - TGO, HKMG, 5Vt - 1P/10Cu
566. 300mm - 28nm - TSMC - HPM - CMOS - TGO, HKMG, 5Vt - 1P/11Cu
567. 300mm - 28nm - TSMC - LP - CMOS - DGO, 3Vt - 1P/7Cu
568. 300mm - 28nm - TSMC - LP - CMOS - DGO, 3Vt - 1P/8Cu
569. 300mm - 28nm - TSMC - LP - CMOS - DGO, 3Vt - 1P/9Cu
570. 300mm - 28nm - TSMC - LP - CMOS - DGO, 3Vt - 1P/10Cu
571. 300mm - 28nm - TSMC - LP - CMOS - DGO, 3Vt - 1P/11Cu
572. 300mm - 28nm - UMC - HPC - CMOS - DGO, HKMG, Res, 4Vt - 1P/8Cu
573. 300mm - 28nm - UMC - HPC - CMOS - DGO, HKMG, Res, 4Vt - 1P/9Cu
574. 300mm - 28nm - UMC - HLP - CMOS - DGO - 1P/9Cu
575. 300mm - 28nm - UMC - HLP - CMOS - DGO - 1P/10Cu
576. 300mm - 28nm - UMC - HLP - CMOS - DGO - 1P/11Cu
577. 300mm - 28nm - UMC - HPM - CMOS - DGO, HKMG - 1P/9Cu
578. 300mm - 28nm - UMC - HPM - CMOS - DGO, HKMG - 1P/10Cu
579. 300mm - 28nm - UMC - HPM - CMOS - DGO, HKMG - 1P/11Cu
580. 300mm - 28nm - UMC - LP - CMOS - DGO - 1P/9Cu
581. 300mm - 28nm - UMC - LP - CMOS - DGO - 1P/10Cu
582. 300mm - 28nm - UMC - LP - CMOS - DGO - 1P/11Cu
583. 300mm - 27nm - Samsung - NA - NAND - NA - 3P/1W/1Cu/1Al
584. 300mm - 26nm - Samsung - NA - DRAM - NA - 2P/1W/1Cu/1Al
585. 300mm - 25nm - Micron - NA - DRAM - NA - 2P/1W/3Cu
586. 300mm - 25nm - SK Hynix - NA - DRAM - NA - M10 - 5P/W/2Cu/Al
587. 300mm - 24nm - Toshiba - NA - NAND - NA - 3P/1W/1Cu/1Al
588. 300mm - 22nm - Global Foundries - FDX-uhp - CMOS - MIM, 4Vt - 1P/8Cu
589. 300mm - 22nm - Global Foundries - FDX-uhp - CMOS - MIM, 4Vt - 1P/9Cu
590. 300mm - 22nm - Global Foundries - FDX-uhp - CMOS - MIM, 4Vt - 1P/10Cu
591. 300mm - 22nm - Global Foundries - FDX-ull - CMOS - DGO, ULL SRAM, 5Vt - 1P/8Cu
592. 300mm - 22nm - Global Foundries - FDX-ull - CMOS - DGO, ULL SRAM, 5Vt - 1P/9Cu
593. 300mm - 22nm - Global Foundries - FDX-ull - CMOS - DGO, ULL SRAM, 5Vt - 1P/10Cu
594. 300mm - 22nm - Global Foundries - FDX-ulp - CMOS - 4Vt - 1P/8Cu
595. 300mm - 22nm - Global Foundries - FDX-ulp - CMOS - 4Vt - 1P/9Cu
596. 300mm - 22nm - Global Foundries - FDX-ulp - CMOS - 4Vt - 1P/10Cu
597. 300mm - 22nm - Global Foundries - FDX-rfa - CMOS - Passives, Thick Metal, 4Vt - 1P/8Cu
598. 300mm - 22nm - Global Foundries - FDX-rfa - CMOS - Passives, Thick Metal, 4Vt - 1P/9Cu
599. 300mm - 22nm - Global Foundries - FDX-rfa - CMOS - Passives, Thick Metal, 4Vt -
1P/10Cu
600. 300mm - 22nm - Intel - P1270 - MG - HKMG, MIM - 1P/1W/9Cu
601. 300mm - 22nm - Intel - P1271 - MG - DGO, HKMG, MIM - 1P/1W/9Cu

602. 300mm - 22nm - Intel - P1271 - MG - DGO, HKMG, MIM - 1P/1W/10Cu
603. 300mm - 22nm - Intel - P1271 - MG - DGO, HKMG, MIM - 1P/1W/11Cu
604. 300mm - 21nm - Samsung - NA - NAND - NA - 3P/1W/1Cu/1Al
605. 300mm - 20nm - Micron - NA - DRAM - NA - Fab 6 - 2P/1W/3Cu
606. 300mm - 20nm - Micron - NA - DRAM - NA - Fab 16 - 2P/1W/3Cu
607. 300mm - 20nm - Samsung - NA - DRAM - NA - 2P/1W/2Cu/1Al
608. 300mm - 20nm - TSMC - SOC - CMOS - DGO, HKMG, 4Vt - 1P/9Cu
609. 300mm - 20nm - TSMC - SOC - CMOS - DGO, HKMG, 4Vt - 1P/10Cu
610. 300mm - 20nm - TSMC - SOC - CMOS - DGO, HKMG, 4Vt - 1P/11Cu
611. 300mm - 19nm - Samsung - NA - NAND - NA - 3P/1W/1Cu/1Al
612. 300mm - 19nm - Toshiba - NA - NAND - NA - 3P/1W/1Cu/1Al
613. 300mm - 16nm - Samsung - NA - NAND - NA - 3P/1W/1Cu/1Al
614. 300mm - 16nm - TSMC - FF+/FFC - MG - DGO, HKMG, 5Vt - 1P/9Cu
615. 300mm - 16nm - TSMC - FF+/FFC - MG - DGO, HKMG, 5Vt - 1P/10Cu
616. 300mm - 16nm - TSMC - FF+/FFC - MG - DGO, HKMG, 5Vt - 1P/11Cu
617. 300mm - 16nm - TSMC - FF+/FFC - MG - DGO, HKMG, 5Vt - 1P/12Cu
618. 300mm - 14nm - Global Foundries - LPE - MG - DGO, CPA, HKMG, 5Vt - 1P/9Cu
619. 300mm - 14nm - Global Foundries - LPE - MG - DGO, CPA, HKMG, 5Vt - 1P/10Cu
620. 300mm - 14nm - Global Foundries - LPE - MG - DGO, CPA, HKMG, 5Vt - 1P/11Cu
621. 300mm - 14nm - Intel - P1272 - MG - HKMG, MIM, 4Vt - 1P/13Cu
622. 300mm - 14nm - Intel - P1273 - MG - DGO, HKMG, MIM, 4Vt - 1P/11Cu
623. 300mm - 14nm - Intel - P1273 - MG - DGO, HKMG, MIM, 4Vt - 1P/12Cu
624. 300mm - 14nm - Intel - P1273 - MG - DGO, HKMG, MIM, 4Vt - 1P/13Cu
625. 300mm - 14nm - Samsung - LPE - MG - DGO, CPA, HKMG, 5Vt - 1P/9Cu
626. 300mm - 14nm - Samsung - LPE - MG - DGO, CPA, HKMG, 5Vt - 1P/10Cu
627. 300mm - 14nm - Samsung - LPE - MG - DGO, CPA, HKMG, 5Vt - 1P/11Cu
628. 300mm - 14nm - UMC - NA - MG - DGO, HKMG, 5Vt - 1P/9Cu
629. 300mm - 14nm - UMC - NA - MG - DGO, HKMG, 5Vt - 1P/10Cu
630. 300mm - 14nm - UMC - NA - MG - DGO, HKMG, 5Vt - 1P/11Cu
631. 300mm - 12nm - TSMC - FF - MG - DGO, HKMG, 4Vt - 1P/10Cu
632. 300mm - 12nm - TSMC - FF - MG - DGO, HKMG, 4Vt - 1P/11Cu
633. 300mm - 12nm - TSMC - FF - MG - DGO, HKMG, 4Vt - 1P/12Cu
634. 300mm - 10nm - Intel - P1274 - MG - HKMG, MIM, 5Vt - 1P/1W/12Cu
635. 300mm - 10nm - Intel - P1275 - MG - DGO, HKMG, MIM, 5Vt - 1P/1W/10Cu
636. 300mm - 10nm - Intel - P1275 - MG - DGO, HKMG, MIM, 5Vt - 1P/1W/11Cu
637. 300mm - 10nm - Intel - P1275 - MG - DGO, HKMG, MIM, 5Vt - 1P/1W/12Cu
638. 300mm - 10nm - Samsung - FF - MG - DGO, HKMG, 5Vt - 1P/10Cu
639. 300mm - 10nm - Samsung - FF - MG - DGO, HKMG, 5Vt - 1P/11Cu
640. 300mm - 10nm - Samsung - FF - MG - DGO, HKMG, 5Vt - 1P/12Cu
641. 300mm - 10nm - TSMC - FF - MG - DGO, HKMG, 4Vt - 1P/10Cu
642. 300mm - 10nm - TSMC - FF - MG - DGO, HKMG, 4Vt - 1P/11Cu
643. 300mm - 10nm - TSMC - FF - MG - DGO, HKMG, 4Vt - 1P/12Cu
644. 300mm - 8nm - Samsung - LPP - MG - DGO, HKMG, 5Vt - 1P/11Cu
645. 300mm - 8nm - Samsung - LPP - MG - DGO, HKMG, 5Vt - 1P/12Cu
646. 300mm - 8nm - Samsung - LPP - MG - DGO, HKMG, 5Vt - 1P/13Cu
647. 300mm - 7nm - Global Foundries - LP - MG - DGO. HKMG, 5Vt - 1P/11Cu
648. 300mm - 7nm - Global Foundries - LP - MG - DGO. HKMG, 5Vt - 1P/12Cu
649. 300mm - 7nm - Global Foundries - LP - MG - DGO. HKMG, 5Vt - 1P/13Cu

- 650. 300mm - 7nm - TSMC - FF - MG - DGO, HKMG, 4Vt - 1P/11Cu
- 651. 300mm - 7nm - TSMC - FF - MG - DGO, HKMG, 4Vt - 1P/12Cu
- 652. 300mm - 7nm - TSMC - FF - MG - DGO, HKMG, 4Vt - 1P/13Cu